



Atty. Dkt. No. 047071-0107

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Harry A. ATWATER, Jr. et al.

Title: WAFER BONDED VIRTUAL  
SUBSTRATE AND METHOD  
FOR FORMING THE SAME

Appl. No.: 10/761,918

Filing Date: 1/20/2004

Examiner: Duy-Vu DEO

Art Unit: 1765

Confirmation 4108  
Number:

**AMENDMENT AND REPLY UNDER 37 CFR 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Non-Final Office Action dated  
May 11, 2006, concerning the above-referenced patent application.

**Amendments to the Specification** begin on page 2 of this document.

**Amendments to the Claims** are reflected in the listing of claims which begins on  
page 3 of this document.

**Remarks/Arguments** begin on page 8 of this document.

Please amend the application as follows: